

Please cancel claims 1-13 without prejudice or disclaimer of the subject matter therein.

Claims 1-13 (canceled)

14.(Original) A planarized ultra fine particle film forming method for forming a planarized ultra fine particle film from a deposited film of ultra fine particles formed by supplying the ultra fine particles to a substrate, the method comprising one or more of a planarizing step of planarizing a surface of the deposited film of the ultra fine particles by blowing planarizing fine particles having a grinding/polishing function at an oblique incidence angle toward the surface of the deposited film.

15.(Original) A planarized ultra fine particle film forming method according to claim 14, wherein the planarizing fine particles are accelerated by using an electrostatic field or gas and blown toward the surface of the deposited film of the ultra fine patterns.

16.(Original) A planarized ultra fine particle film forming method according to claim 14, wherein the incidence angle of a flow of the planarizing fine particles relative to the substrate is in a range of - 60 degrees to - 5 degrees or + 5 degrees to + 60 degrees.

17.(currently amended) A planarized ultra fine particle film forming method according to claim 14,

wherein the planarizing fine particles have a same composition as that of the ultra fine particles.

18.(currently amended) A planarized ultra fine particle film forming method according to claim 14, wherein the planarizing fine particles have a particle diameter larger than that of the ultra fine particles.

19.(currently amended) A planarized ultra fine particle film forming method according to claim 14, wherein the planarizing fine particles have a rigidity higher than that of the ultra fine particles.

20.(Original) A planarized ultra fine particle film forming apparatus for forming a planarized ultra fine particle film from a deposited film of ultra fine particles formed by supplying the ultra fine particles to a substrate, wherein planarizing fine particles having a grinding/polishing function are blown at an oblique incidence angle toward the surface of the deposited film.

21.(Original) A planarized ultra fine particle film forming apparatus according to claim 20, further comprising a spray apparatus such as a nozzle and an electrostatic acceleration gun for jetting out, at the same time or separately, the ultra fine particles and the planarizing having the grinding/polishing function, toward the substrate, and a center axis of a jet flow of said spray apparatus being set in

an incidence angle range of - 60 degrees to - 5 degrees or + 5 degrees to + 60 degrees relative to a surface of the substrate.

22.(Original) A planarized ultra fine particle film forming apparatus according to claim 20, further comprising a spray apparatus such as a nozzle and an electrostatic acceleration gun for jetting out, at the same time or separately, the ultra fine particles and the planarizing having the grinding/polishing function, toward the substrate, and a flow of the ultra fine particles or planarizing particles jetted out from said spray apparatus being set to have a conical shape having an incidence angle range of - 60 degrees to - 5 degrees or + 5 degrees to + 60 degrees about a center axis of a jet flow of said spray apparatus.